



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

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Examiner: Alonzo Chambliss

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Application No.: 10/681,584

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Group Art Unit: 2814

Filed: October 8, 2003

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Date: 26 April 2005.

Title: **Semiconductor multi-package  
module having inverted second package  
and including additional die or stacked  
package on second package**

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 26 April 2005.

Signed

Bill Kennedy

AMENDMENT

Dear Sir:

Responsive to the Office action mailed October 26, 2004, kindly amend the application as follows.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the **Listing of Claims**, which begins on page 5 of this paper.

**Amendments to the Drawings** begin on page 8 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

**Remarks** begin on page 9 of this paper.

An **Appendix** including amended drawing figures is attached following page 15 of this paper.